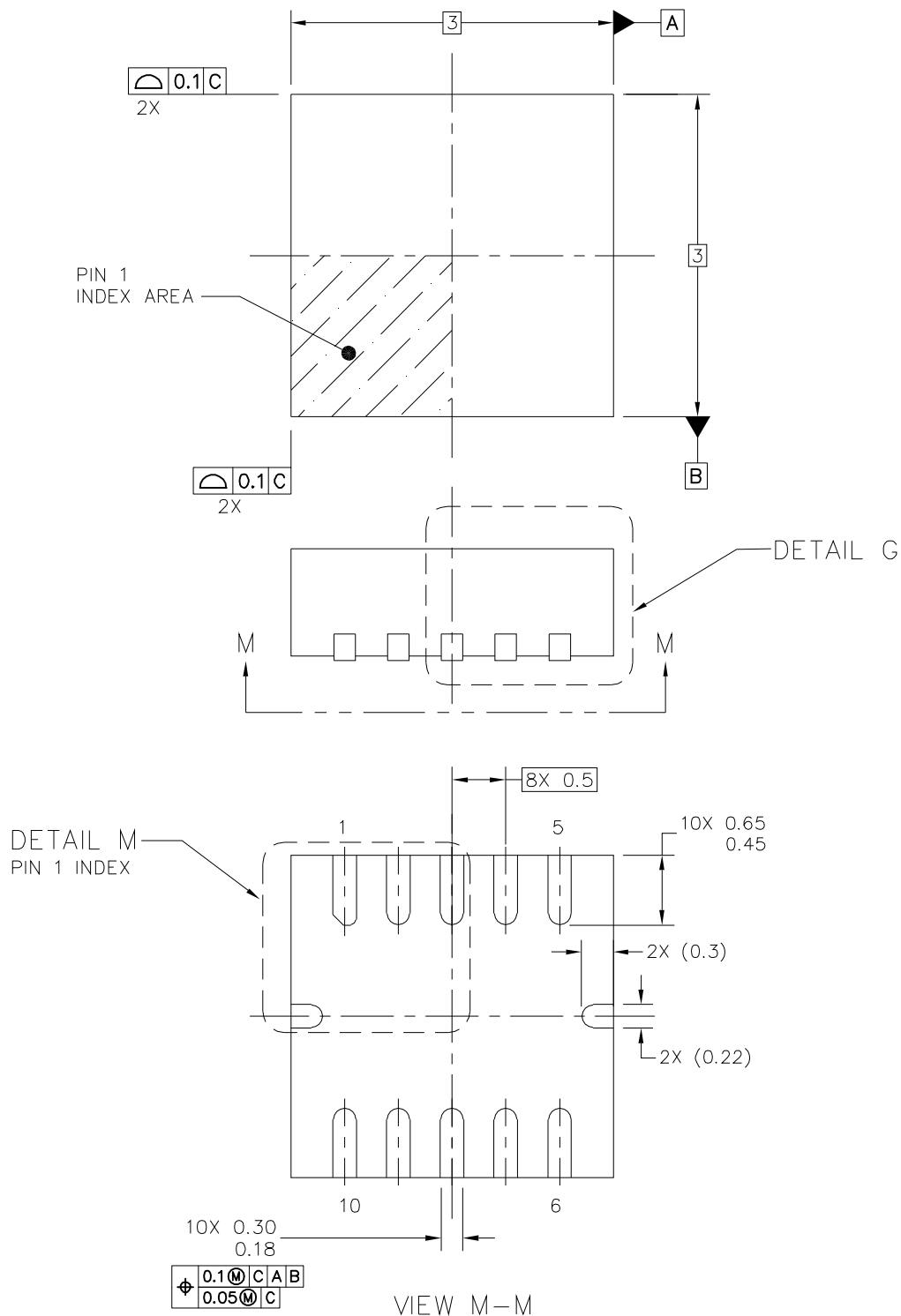
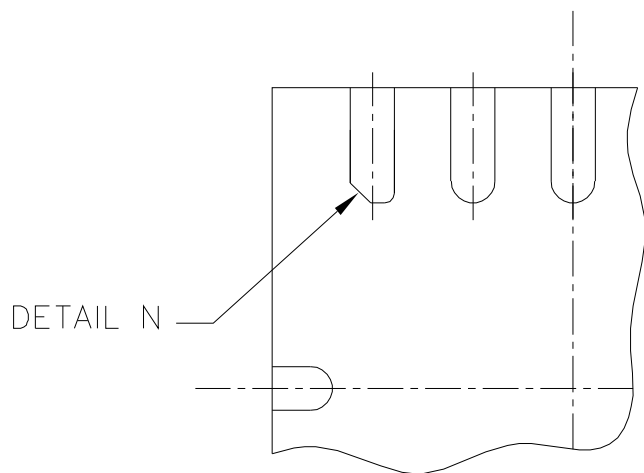


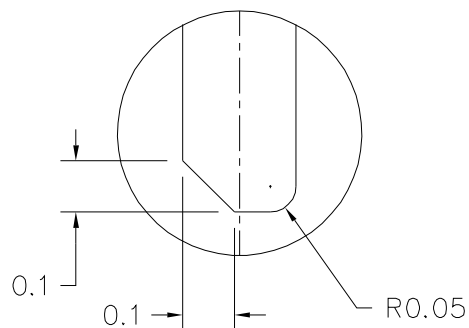


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TITLE: DUAL FLAT NO LEAD COL PACKAGE (DFN-COL) 10 TERMINAL, 0.5 PITCH (3 X 3 X 0.9)	DOCUMENT NO: 98ASA10816D REV: C	
	STANDARD: NON JEDEC	
	SOT1616-1	19 JAN 2016

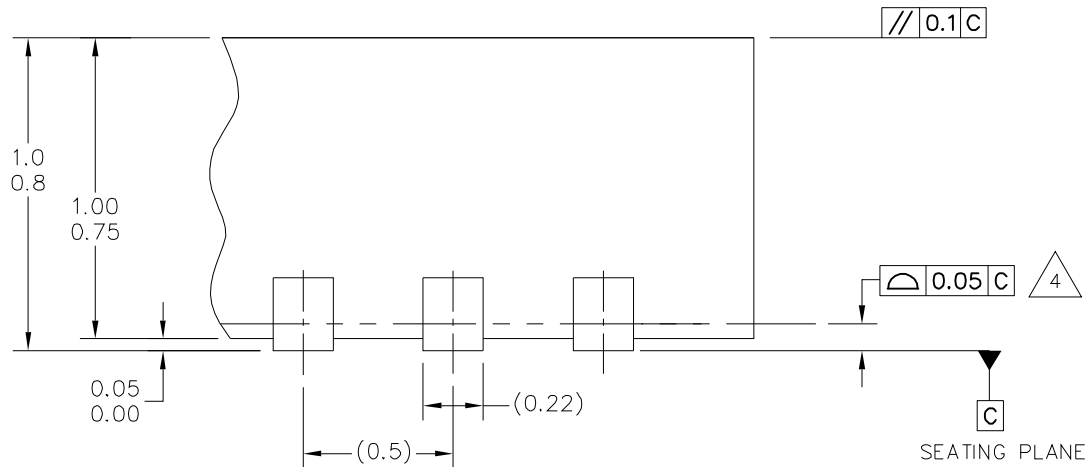


DETAIL N

DETAIL M
PIN 1 BACKSIDE INDEX



DETAIL N
PIN 1 BACKSIDE INDEX



DETAIL G

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		STANDARD: NON JEDEC	
		SOT1616-1	19 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND ALL OTHR BOTTOM SURFACE METALLIZATION.
5. MIN. METAL GAP SHOULD BE 0.2MM.

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